



**Uncompromising and leading solutions** 

# 357IC2

World-Best Performance 3D Solder Paste Inspection

- The strongest printing process optimization tool
- The world's best measurement accuracy and reliability
- Advanced model for a wide production environment



**User-friendly Software** 



3D Data based SMT Process Control System



Real Time Warp Compensation Solution







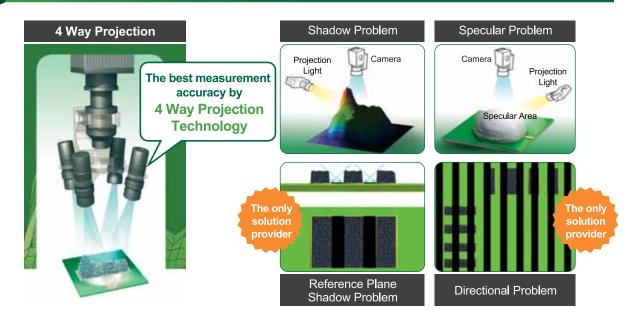


World-Best Performance 3D Solder Paste Inspection



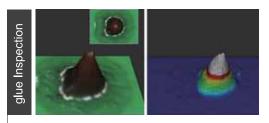


## **Unique 3D SPI that provides Solutions for Conventional SPI Bottlenecks**

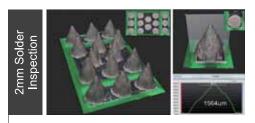




## **Wide Inspection Objects Coverage**



3D measurement capability for glue, silver epoxy and more non-solder materials



Increased measurement range up to 2mm, \*Patented enabled by Multi-Frequency Moiré Technology



## **Warp Compensation Solution**



Optional 🗹







- Z-tracking 3D Compensation Solution
- Koh Young's Multi-Frequency Moiré Technology applied
- Real time measurement and compensation of board warp, with respect to the ideal plane
- Real time online provision of high quality PCB images with measurement data

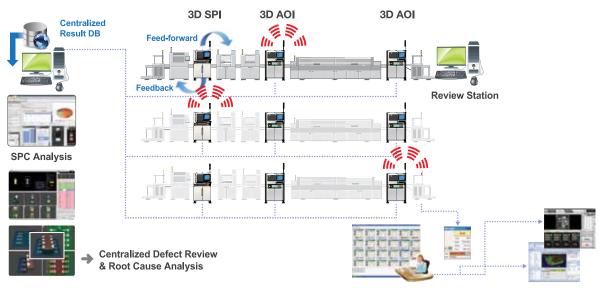
#### Pad Referencing 2D Compensation Solution

- · Automatic reference teaching by using high quality IR light
- Real time matching of the PCB pad locations with the ideal PCB stencil design as defined by the CAD file



## 3D Data based SMT Process Control System

### Koh Young's KSMART Solution

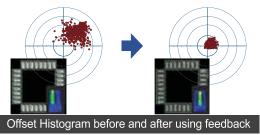


Remote Process Review & Multi-Line Monitoring & Fine Tuning



#### Closed Loop Real Time Screen Printer Communication

Optional 🗹



- Real time communication of printing process monitoring data with screen printers
- Result reporting after optimization by Koh Young's SPC software

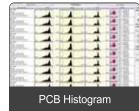


- Real time communication of pick-and-place process monitoring data with mounters
- Supports process optimization by controlling panels containing defects



### SPC Plus Printing Process Optimization Tool

- Review, diagnosis and optimization of printing, pick-and-place and reflow process
- 3D data based SPI-AOI communication solution
- Traces root cause of defects by storing and communicating inspection results from Koh Young's 3D SPI and 3D AOI Systems







#### KSMART LINKO

#### KSMART Link Communication Solution





- Provides intuitive statistical process analysis data by using reliable 3D measurement data
- Communicates with a wide range of production management systems

## Must-check Requirements of 3D SPI System



Requiremo	ents	Solutions		
Shadow Pro	oblem Solution			
Specular Pr	oblem Solution			
Reference Plane Shadow Solution		<ul> <li>3D Shadow Free Moiré Technology &amp; 4 Way Projection</li> </ul>		
	Problem Solution			
			- 1 D - (	- \
Real Time PCB Warp Compensation (2D+3D Solution)		Warp Compensation (Pad Referencing + Z-tracking)		
Operator User-friendliness		Renewal GUI, Real Color 3D Image		
Inspection Range		• Up to 2mm		
Foreign Material Inspection		3D Foreign Material Inspection		
Inspection Items	Metrology Capability	Volume, Area, Height, Offset, Bridging, Shape Deformity, Coplanarity		
	Types of Defects	Insufficient/Excessive/Missing Paste, Bridging, Shape Deformity, Paste Offset, Coplanar		
	Camera Resolution	10µm	15µm	20µm
	FOV Size	20×20mm(0.79×0.79 inch)	30×30mm(1.18×1.18 inch)	40×40mm(1.57×1.57 inch)
	Full 3D Inspection Speed	15.2~55.9 cm²/sec (Inspe	ection speed varies by PCB a	and inspection condition.)
	Min. Distance between Paste Deposit	100µm (3.94 mils)	150µm (5.91 mils)	200µm (7.87 mils)
	Camera	4M Pixel Camera		
	Illumination	IR-RGB LED Dome Styled Illumination		
Inspection	Z Resolution	• 0.37µm		
Performance	Height Accuracy (on KY Calibration Target)	• 1μm		
	X,Y Accuracy	2.5 nano meter (PZT Accuracy)		
	01005 Inspection Capacity Gage R&R (±50% tolerance)	• < 10% at 6σ		
	Max. Inspection Size	• 10×10mm 0.39×0.39 inch		
	Max. Inspection Height  Min. Distance between PADs	• 2 mm 78.74 mils		
	Various colored PCB Inspection	<ul> <li>100 μm (150 μm paste height)</li> <li>3.94 mils (5.91 mils paste height)</li> <li>Possible</li> </ul>		
	Various Colored FCB Inspection	- F055IDIE		
PCB Handling	Conveyor Width Adjustment	Automatic		
	Conveyor Fix Type	Front / Rear Fixed (factory setting)		
Software	Supported Input Format	Gerber data (274X, 274D), ODB++ (optional)		
	Programming S/W	• ePM-SPI		
	Statistical Process Control Tool	<ul> <li>SPC Plus:</li> <li>Histogram, X-bar &amp; R-Chart, X-bar &amp; S-Chart, Cp &amp; Cpk, %Gage R&amp;R</li> <li>Real Time SPC &amp; Multiple Display</li> <li>SPC Alarm</li> </ul>		
		KSMART Remote Monitoring System		
	Operator User-friendliness	<ul> <li>Library Station: Size Dependent Library for Inspection Condition Setting</li> <li>KYCal: Auto Camera Calibration, Auto Illumination Calibration, Auto Height Calibration</li> </ul>		
	Operating System	Windows 7 Ultimate 64bit		
Add-on Solutions	1D & 2D Handy Barcode Reader	Offline SPC Plus Station	n	Review Station
	<ul> <li>1D &amp; 2D Inline Barcode Reader</li> </ul>	Standard Calibration Target     Closed Loop		
	<ul> <li>Offline Programming Station</li> </ul>	KSMART Remote Monitoring System     UPS		

\* Above specifications are subject to change without notice.

	L	DL	XL	
Max. PCB Size	510X510mm (20X20 inch)	Dual: 510X430mm (20X16.9 inch) Single: 510X250mm (20X9.8 inch)	810X610mm (31.9X24 inch)	
Min. PCB Size	50X50mm			
PCB Thickness	0.4~5mm (0.015~0.2 inch)		0.5~8mm (0.02~0.3 inch)	
Max. PCB Weight	5kg (11lbs)		10kg (22lbs)	
Machine Weight	600Kg(1322 lbs)		850Kg (1874 lbs)	
Bottom Side Clearance	30mm(1.18 inch)			
Supplies	200~240VAC, 50/60Hz Single Phase, 5Kgf/cmm			
W	1000mm (39.3 inch)		1310mm (51.5 inch)	
D	1230mm (48.4 inch)		1475mm (57 inch)	
Н	1602mm (63 inch)		1636mm (64.4 inch)	
F	898mm (	35.3 inch)	1083mm (42.6 inch)	

